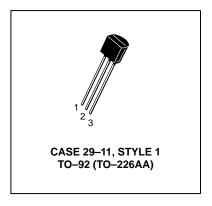


Amplifier Transistor NPN Silicon

MPSA20

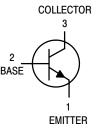
MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|-----------------------------------|-------------|----------------|
| Collector–Emitter Voltage | V _{CEO} | 40 | Vdc |
| Collector-Base Voltage | V _{CBO} | 4.0 | Vdc |
| Collector Current — Continuous | I _C | 100 | mAdc |
| Total Device Dissipation @ T _A = 25°C Derate above 25°C | P _D | 625 5.0 | mW mW/°C |
| Total Device Dissipation @ T _C = 25°C Derate above 25°C | P _D | 1.5 12 | Watts mW/°C |
| Operating and Storage Junction Temperature Range | T _J , T _{stg} | -55 to +150 | °C |



THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit | |
|---|-----------------------|------|------|--|
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}^{(1)}$ | 200 | °C/W | |
| Thermal Resistance, Junction to Case | $R_{	heta JC}$ | 83.3 | °C/W | |



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | | Min | Max | Unit | |
|--|----------------------|-----|-----|------|--|
| OFF CHARACTERISTICS | | | | | |
| Collector–Emitter Breakdown Voltage ⁽²⁾ (I _C = 1.0 mAdc, I _B = 0) | V _{(BR)CEO} | 40 | _ | Vdc | |
| Emitter–Base Breakdown Voltage ($I_E = 100 \mu Adc$, $I_C = 0$) | V _{(BR)EBO} | 4.0 | _ | Vdc | |
| Collector Cutoff Current $(V_{CB} = 30 \text{ Vdc}, I_E = 0)$ | I _{CBO} | | 100 | nAdc | |

- 1. $R_{\theta JA}$ is measured with the device soldered into a typical printed circuit board. 2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (Continued)

| Characteristic | Symbol | Min | Max | Unit |
|---|----------------------|-----|------|------|
| ON CHARACTERISTICS | <u>.</u> | | | |
| DC Current Gain ⁽²⁾ (I _C = 5.0 mAdc, V _{CE} = 10 Vdc) | h _{FE} | 40 | 400 | _ |
| Collector–Emitter Saturation Voltage (I _C = 10 mAdc, I _B = 1.0 mAdc) | V _{CE(sat)} | _ | 0.25 | Vdc |
| SMALL-SIGNAL CHARACTERISTICS | <u>.</u> | | | |
| Current–Gain — Bandwidth Product ⁽²⁾ (I _C = 5.0 mAdc, V _{CE} = 10 Vdc, f = 100 MHz) | f _T | 125 | _ | MHz |
| Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz) | C _{obo} | _ | 4.0 | pF |

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

EQUIVALENT SWITCHING TIME TEST CIRCUITS

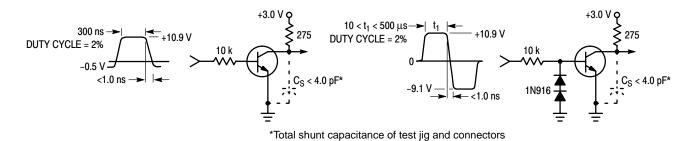


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

TYPICAL NOISE CHARACTERISTICS

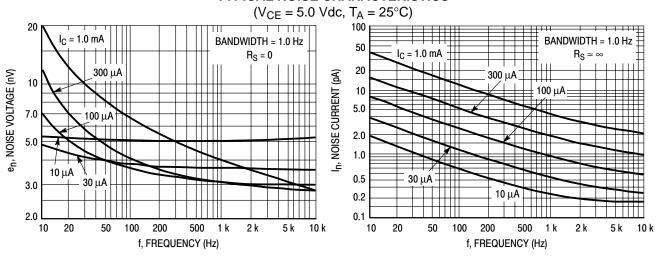


Figure 3. Noise Voltage

Figure 4. Noise Current

NOISE FIGURE CONTOURS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

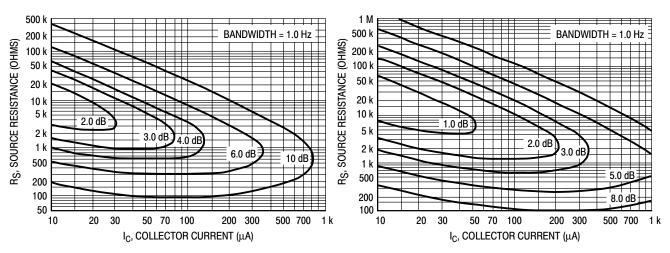


Figure 5. Narrow Band, 100 Hz

Figure 6. Narrow Band, 1.0 kHz

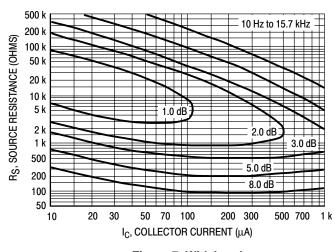


Figure 7. Wideband

Noise Figure is defined as:

$$NF = 20 \log_{10} \left(\frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right)^{1/2}$$

en = Noise Voltage of the Transistor referred to the input. (Figure 3)

I_n = Noise Current of the Transistor referred to the input. (Figure 4)

 $K = Boltzman's Constant (1.38 x 10^{-23} j/^{\circ}K)$

Γ = Temperature of the Source Resistance (°K)

R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS

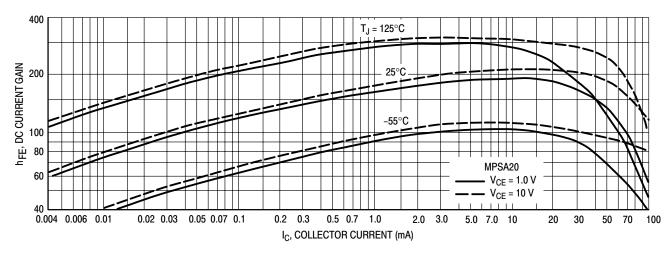


Figure 8. DC Current Gain

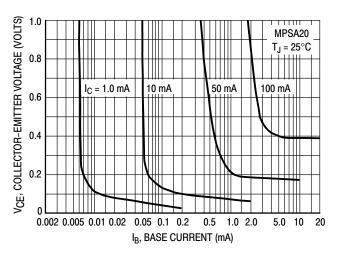


Figure 9. Collector Saturation Region

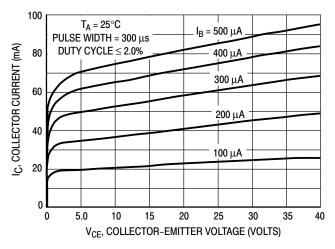


Figure 10. Collector Characteristics

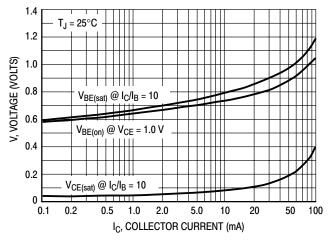


Figure 11. "On" Voltages

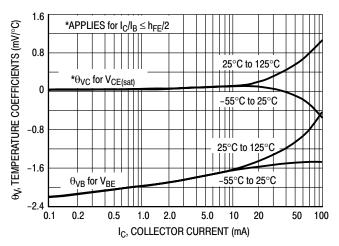
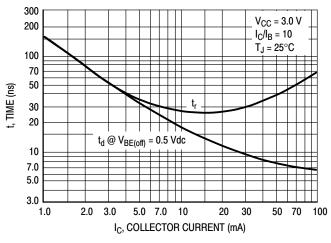


Figure 12. Temperature Coefficients

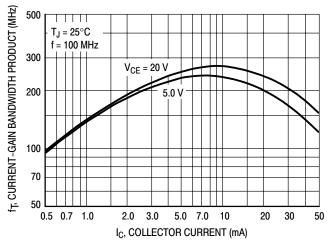
TYPICAL DYNAMIC CHARACTERISTICS



1000 700 500 300 200 100 70 50 V_{CC} = 3.0 V30 $I_{\rm C}/I_{\rm B}=10$ 20 $I_{B1}=I_{B2}$ $T_J = 25^{\circ}C$ 2.0 3.0 10 30 70 100 1.0 5.0 7.0 20 50 I_C, COLLECTOR CURRENT (mA)

Figure 13. Turn-On Time

Figure 14. Turn-Off Time



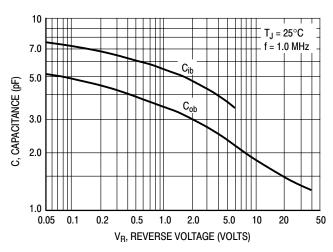
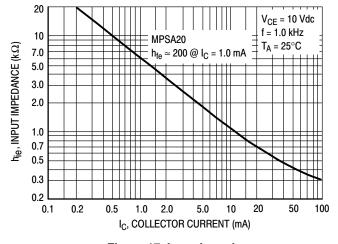


Figure 15. Current-Gain — Bandwidth Product

Figure 16. Capacitance



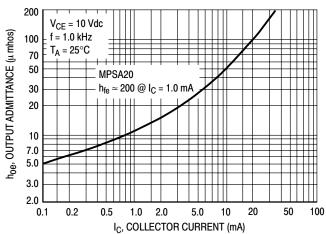


Figure 17. Input Impedance

Figure 18. Output Admittance

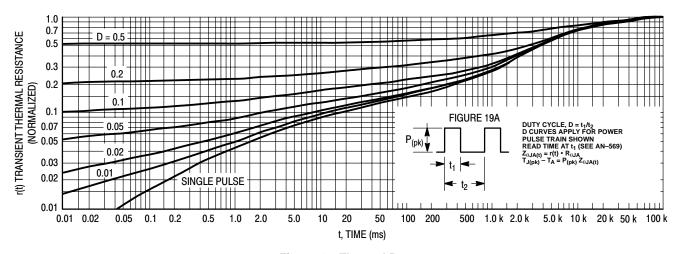


Figure 19. Thermal Response

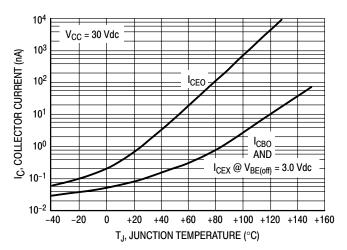


Figure 19a:

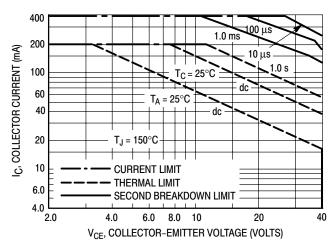


Figure 20.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19A. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 19 was calculated for various duty cycles.

To find $Z_{\theta JA(t)}$, multiply the value obtained from Figure 19 by the steady state value $R_{\theta JA}$.

Example:

Dissipating 2.0 watts peak under the following conditions:

$$t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$$

Using Figure 19 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

The peak rise in junction temperature is therefore

$$\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$$

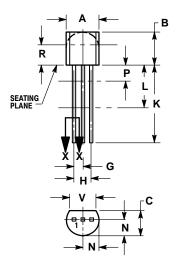
For more information, see AN-569.

The safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 20 is based upon $T_{J(pk)} = 150^{\circ}C$; T_{C} or T_{A} is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 19. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AL





TYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

| | INCHES | | MILLIMETERS | | |
|-----|--------|-------|-------------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.175 | 0.205 | 4.45 | 5.20 | |
| В | 0.170 | 0.210 | 4.32 | 5.33 | |
| С | 0.125 | 0.165 | 3.18 | 4.19 | |
| D | 0.016 | 0.021 | 0.407 | 0.533 | |
| G | 0.045 | 0.055 | 1.15 | 1.39 | |
| Н | 0.095 | 0.105 | 2.42 | 2.66 | |
| J | 0.015 | 0.020 | 0.39 | 0.50 | |
| K | 0.500 | | 12.70 | | |
| L | 0.250 | | 6.35 | | |
| N | 0.080 | 0.105 | 2.04 | 2.66 | |
| P | | 0.100 | | 2.54 | |
| R | 0.115 | | 2.93 | | |
| ٧ | 0.135 | | 3.43 | | |

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